

# PC4H520NIP

## Mini-flat Half-pitch Package Darlington Phototransistor Output High Collector-emitter Voltage Photocoupler



#### ■ Description

**PC4H520NIP** contains a IRED optically coupled to a phototransistor.

It is packaged in a 4-pin Mini-flat, Half pitch type. Input-output isolation voltage(rms) is 2.5kV. Collector-emitter voltage is 350V and CTR is MIN. 1000% at input current of 1mA.

#### **■** Features

- 1. 4-pin Mini-flat Half pitch package (Lead pitch : 1.27mm)
- Double transfer mold package (Ideal for Flow Soldering)
- 3. High collector-emitter voltage (V<sub>CEO</sub>: 350V)
- 4. Darlington phototransistor output (CTR : MIN.1000%  $I_F=ImA, V_{CE}=2V$ )
- 5. Isolation voltage between input and output ( $V_{iso(rms)}$ : 2.5kV)

#### ■ Agency approvals/Compliance

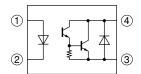
- 1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. **PC4H52**)
- 2. Package resin : UL flammability grade (94V-0)

### ■ Applications

1. Modems



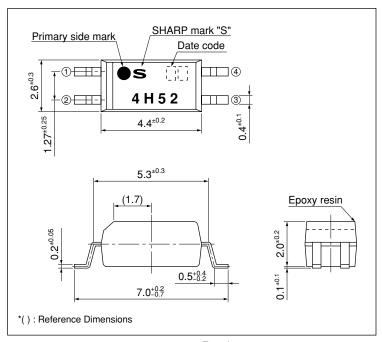
### ■ Internal Connection Diagram



- ① Anode
- ③ Cathode
- 4 Emitter
- ⑤ Collector

### **■** Outline Dimensions

(Unit: mm)



Product mass: approx. 0.05g



### Date code (2 digit)

	1st o	digit		2nd digit		
	Year of p	roduction		Month of production		
A.D.	Mark	A.D	Mark	Month	Mark	
1990	A	2002	P	January	1	
1991	В	2003	R	February	2	
1992	С	2004	S	March	3	
1993	D	2005	T	April	4	
1994	Е	2006	U	May	5	
1995	F	2007	V	June	6	
1996	Н	2008	W	July	7	
1997	J	2009	X	August	8	
1998	K	2010	A	September	9	
1999	L	2011	В	October	0	
2000	M	2012	С	November	N	
2001	N	:	:	December	D	

repeats in a 20 year cycle

Country of origin Japan



■ Absolute Maximum Ratings

	■ Absolute Maximum Ratings (T <sub>a</sub> =25°C						
	Parameter	Symbol	Rating	Unit			
Input	Forward current	$I_{\mathrm{F}}$	50	mA			
	*2 Peak forward current	$I_{FM}$	1	A			
	Reverse voltage	$V_R$	6	V			
	*1 Power dissipation	P	70	mW			
Output	Collector-emitter voltage	$V_{CEO}$	350	V			
	Emitter-collector voltage	$V_{ECO}$	0.1	V			
	Collector current	$I_C$	120	mA			
	*1 Collector power dissipation	$P_{C}$	180	mW			
*17	Total power dissipation	$P_{tot}$	210	mW			
Operating temperature		Topr	-40 to +100	°C			
Storage temperature		$T_{stg}$	-55 to +125	°C			
*3 Isolation voltage		V <sub>iso (rms)</sub>	2.5	kV			
*4 Soldering temperature		$T_{sol}$	260	°C			

<sup>\*1</sup> Mounted glass epoxy PCB (Size : 20mm×20mm×1.6mm)

\*2 Pulse width≤100µs, Duty ratio : 0.001

\*3 40 to 60%RH, AC for 1 minute, f=60Hz

\*4 For 10s

### **■** Electro-optical Characteristics

 $(T_a=25^{\circ}C)$ 

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
	Forward voltage		$V_F$	I <sub>F</sub> =10mA	-	1.2	1.4	V
Input	Reverse current		$I_R$	$V_R=4V$	-	-	10	μΑ
	Terminal capacitance		$C_{t}$	V=0, $f=1kHz$	-	30	250	pF
Output	Collector dark current		$I_{CEO}$	$V_{CE}=200V, I_{F}=0$	-	-	200	μΑ
	Collector-emitter breakdown voltage		$\mathrm{BV}_{\mathrm{CEO}}$	$I_{C}=0.1 \text{ mA}, I_{F}=0$	350	ı	-	V
Transfer charac- teristics	Current transfer ratio		$I_{C}$	$I_F=1mA, V_{CE}=2V$	10	40	120	mA
	Collector-emitter saturation voltage		V <sub>CE (sat)</sub>	$I_F = 20 \text{mA}, I_C = 100 \text{mA}$	-	-	1.4	V
	Isolation resistance		$R_{\rm ISO}$	DC500V, 40 to 60%RH	5×10 <sup>10</sup>	1×10 <sup>11</sup>	-	Ω
	Floating capacitance		$C_{\mathrm{f}}$	V=0, $f=1MHz$	_	0.6	1.0	pF
	Cut-off frequency		$f_C$	$V_{CE}$ =2V, $I_{C}$ =20mA, $R_{L}$ =100 $\Omega$ -3dB	1	7	-	kHz
	Response time	Rise time	$t_r$	$V_{CE}=2V$ , $I_{C}=20$ mA, $R_{I}=100\Omega$	_	100	300	μs
		Fall time	$t_{\rm f}$	v CE-2 v , IC-20IIIA, KL=100\$2	_	20	100	μs



Fig.1 Forward Current vs. Ambient Temperature

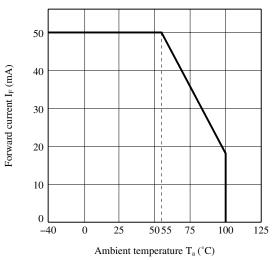


Fig.3 Collector Power Dissipation vs. Ambient Temperature

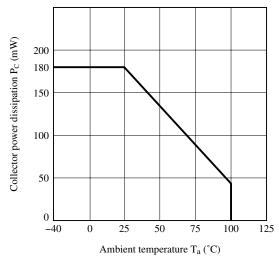


Fig.5 Peak Forward Current vs. Duty Ratio

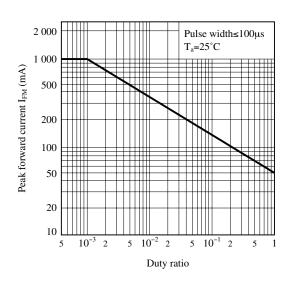


Fig.2 Diode Power Dissipation vs. Ambient Temperature

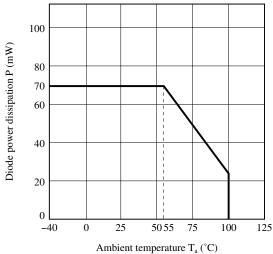


Fig.4 Total Power Dissipation vs. Ambient Temperature

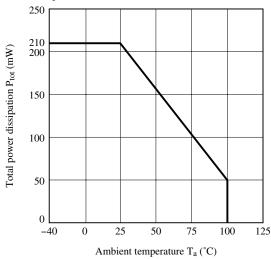


Fig.6 Forward Current vs. Forward Voltage

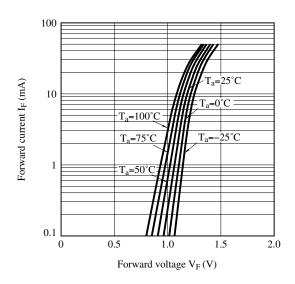




Fig.7 Current Transfer Ratio vs. Forward Current

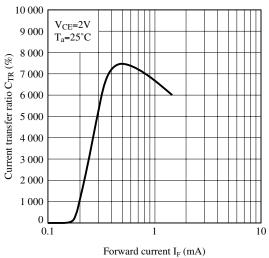


Fig.9 Collector Current vs. Forward Current

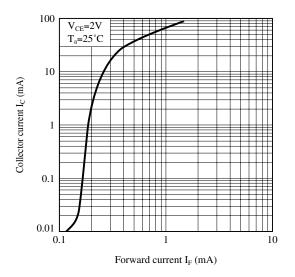


Fig.11 Collector Dark Current vs. Ambient Temperature

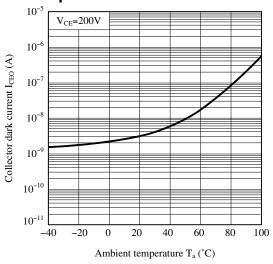


Fig.8 Collector Current vs. Collector-emitter Voltage

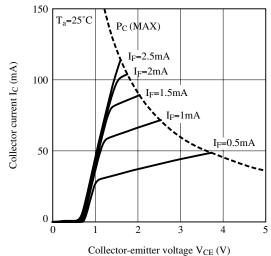


Fig.10 Relative Current Transfer Ratio vs.
Ambient Temperature

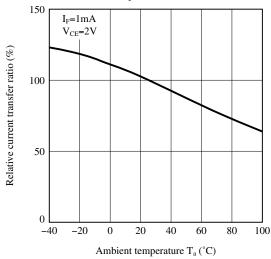
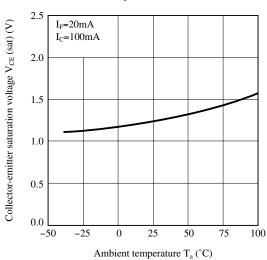


Fig.12 Collector Sayuration Voltage vs.
Ambient Temperature

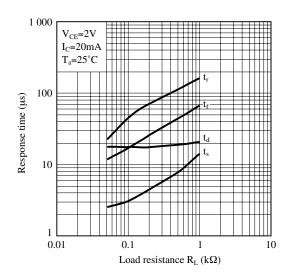


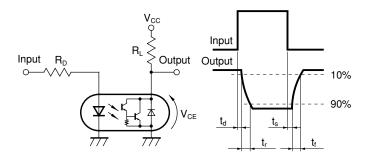
Sheet No.: D2-A02801EN



### Fig.13 Response Time vs. Load Resistance

Fig.14 Test Circuit for Response Time





Please refer to the conditions in Fig.13

Remarks: Please be aware that all data in the graph are just for reference and not for guarantee.



### ■ Design Considerations

### Design guide

While operating at I<sub>F</sub><1.0mA, CTR variation may increase.

Please make design considering this fact.

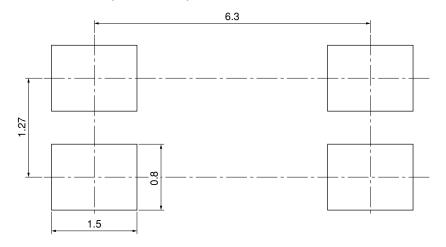
This product is not designed against irradiation and incorporates non-coherent IRED.

### Degradation

In general, the emission of the IRED used in photocouplers will degrade over time.

In the case of long term operation, please take the general IRED degradation (50% degradation over 5years) into the design consideration.

### Recommended Foot Print (reference)



(Unit: mm)

<sup>☆</sup> For additional design assistance, please review our corresponding Optoelectronic Application Notes.



#### ■ Manufacturing Guidelines

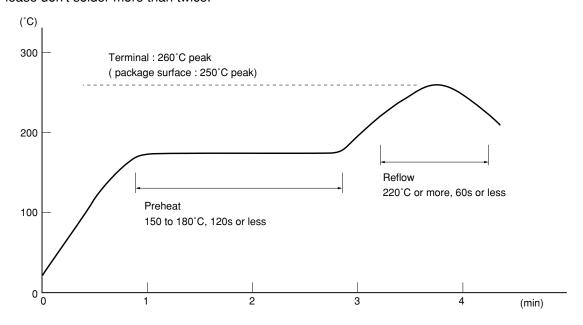
### Soldering Method

#### Reflow Soldering:

Reflow soldering should follow the temperature profile shown below.

Soldering should not exceed the curve of temperature profile and time.

Please don't solder more than twice.



#### Flow Soldering:

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 260°C and within 10s.

Preheating is within the bounds of 100 to 150°C and 30 to 80s.

Please don't solder more than twice.

#### Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C.

Please don't solder more than twice.

#### Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



#### Cleaning instructions

#### Solvent cleaning:

Solvent temperature should be 45°C or below Immersion time should be 3minutes or less

#### Ultrasonic cleaning:

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

#### Recommended solvent materials:

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

#### Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this device.

Regulation substances: CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

Sheet No.: D2-A02801EN



### ■ Package specification

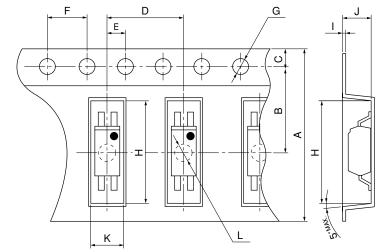
### ● Tape and Reel package

Package materials Carrier tape : PS

Cover tape: PET (three layer system)

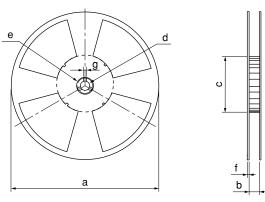
Reel: PS

### Carrier tape structure and Dimensions



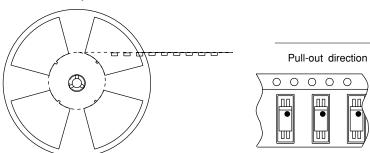
**Dimensions List** (Unit: mm) C Е F D G A 12.0±0.3  $5.5^{\pm0.1}$  $1.75^{\pm0.1}$  $8.0^{\pm0.1}$  $2.0^{\pm0.1}$  $4.0^{\pm0.1}$  $\phi 1.5^{+0.1}_{-0}$ Н K L Ι J  $7.5^{\pm0.1}$  $0.3^{\pm0.05}$ 2.3<sup>±0.1</sup> 3.1<sup>±0.1</sup> φ1.6<sup>+0.1</sup>

### Reel structure and Dimensions



Dimension	ns List	(Unit: mm)		
a	b	c	d 13 <sup>±0.5</sup>	
330	13.5 <sup>±1.5</sup>	100±1.0		
e	f	g		
23±1.0	2.0±0.5	2.0 <sup>±0.5</sup>		

### Direction of product insertion



[Packing: 3 000pcs/reel]



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  - --- Consumer electronics
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- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.
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